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D. Scott
7-6-02

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF :
TSUYOSHI WAKISAKA ET AL : EXAMINER:
SERIAL NO:10/080,121 :
FILED: FEBRUARY 22, 2002 : GROUP ART UNIT:
FOR: SEMICONDUCTOR LASER :
DEVICE AND SEMICONDUCTOR
LASER MODULE

PRELIMINARY AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

Prior to the examination on the merits, please amend the above-identified patent application as follows:

IN THE SPECIFICATION

Page 3, line 32 through page 4, lines 1-9, please replace as follows:

a [Moreover, as shown by the arrow YB in Fig. 16, because the total of four junction faces such as two junction faces corresponding to the metallic thin films 102a and 102b, the junction face between the carrier 101 and the base 106, and the junction face between the base 106 and the Peltier module 107 are present on the heat conducting path between the semiconductor laser element 103 and the Peltier module 107, the heating action or cooling action by the Peltier module 107 is deteriorated whenever